BLC Range

Vapour Phase Reflow Furnaces for optimal soldering quality and performance





+ TECHNICAL

Optimal soldering quality.

+ FINANCIAL

The most cost-effective solution on the market.

+ ECO-FRIENDLY

Environmentally friendly.



The new BLC range, available in both batch and in-line versions with a compact footprint, is ideally suited for medium to large-scale assembly production. These furnaces offer maximum flexibility and soldering quality thanks to a wide range of features. Its dual-process chamber design, oxygen-free reflow without nitrogen, total absence of overheating, and very low power consumption significantly reduce operating costs compared to conventional reflow systems. The large touchscreen and new user interface ensure easy, intuitive, and safe operation.



General

- 3 models available for different board sizes/production
- Compact footprint
- Dual-process chamber design
- Soldering without oxygen or added nitrogen
- No risk of overheating assemblies
- Low power consumption



Features

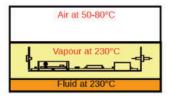
- · Unlimited programme memory capacity
- Simple and user-friendly 15" touchscreen interface
- · Continuous machine data logging
- · Wide range of pre-set soldering profiles
- Low fluid consumption thanks to dual-chamber design and fluid recovery system
- Integrated ventilated cooling system
- Minimal maintenance and wear (all moving parts outside vapour zone)
- 4 internal channels for optimised temperature measurement and profiling
- Energy management system
- Controlled fluid level + automatic filtration
- Automated infeed/outfeed loading



Technical Specifications

- IPS, Intelligent Profiling System for:
 - Temperature-regulated profiles (SVTC: Soft Vapour Temperature Control)
 - · Guided mode: setup and profiling in a single step
- Leaded and lead-free soldering with a single fluid for different peak temperatures
- Integrated profiling software without external data logger
- Syncro mode (hot basket / cold basket)
- Maintenance-free transport system (patented)
- · Easy access to the vapour chamber

Operating principle diagram:



SVP levels Total of 20 positions

The different vapour positions in SVP mode enable the desired optimal profile (precise control and instant change of thermal ramp up to reflow peak)



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- IPSC function (guided mode for control and recording of assembly profile)
- Rapid Cooling System (RCS) (patented)
- IR heating element system (patented)
- Process data recording and analysis software (TRS system)
- Integrated complete Windows PC (HMI)
- Barcode system for automatic programme change, traceability and unlimited storage
- Additional process temperature measurement channels
- Multi-level mode for easy change of soldering heights
- Adapter for top/bottom side PCB reflow
- Backup power module (UPS)
- In-line operation module
- · Additional front cooling unit
- · Self-contained cooling unit



Model	Overall Length (mm)	Depth (mm)	Height (mm)	Weight (kg)	Max Board Size - Batch (mm)	Max Board Size - Inline(mm)	Fluid Capacity (kg)	Water Connection	Water Flow	Max Heating Power (kW)	Power Consumption (kWh)	Electrical Supply	Main Fuse
BLC 420	1060	1960	1320	520	450 x 540 x 80	na	15	1/2" / 2,5 - 5 bar	3 l/min	6.4	2.6	230/400 VAC, 50/60 Hz (3 phases, neutre et terre)	20A "gl" ou "C"
BLC 620	1260			650	650 x 540 x 80	na	20		31/111111	7.8	3.2		25A "gl" ou "C"
BLC 820	1460			780	850 x 540 x 80	na	25		3,5 l/min	10.4	3.6		32A "gl" ou "C"
BLC 620i	2020	- 2490	1470	920	650 x 540 x 80mm	- 630 x 400 x 55	20		3 l/min	7.8	3.2		20A "gl" ou "C"
BLC 820i	2220			1070	850 x 540 x 80mm		25		3,5 l/min	10.4	3.6		32A "gl" ou "C"

